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Shimada et al.

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(54) **SEMICONDUCTOR MANUFACTURING EQUIPMENT**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** D13/182, D13/184; 118/500, 719; 250/307, 310, 311; 414/217, 935, 936, 937
See application file for complete search history.

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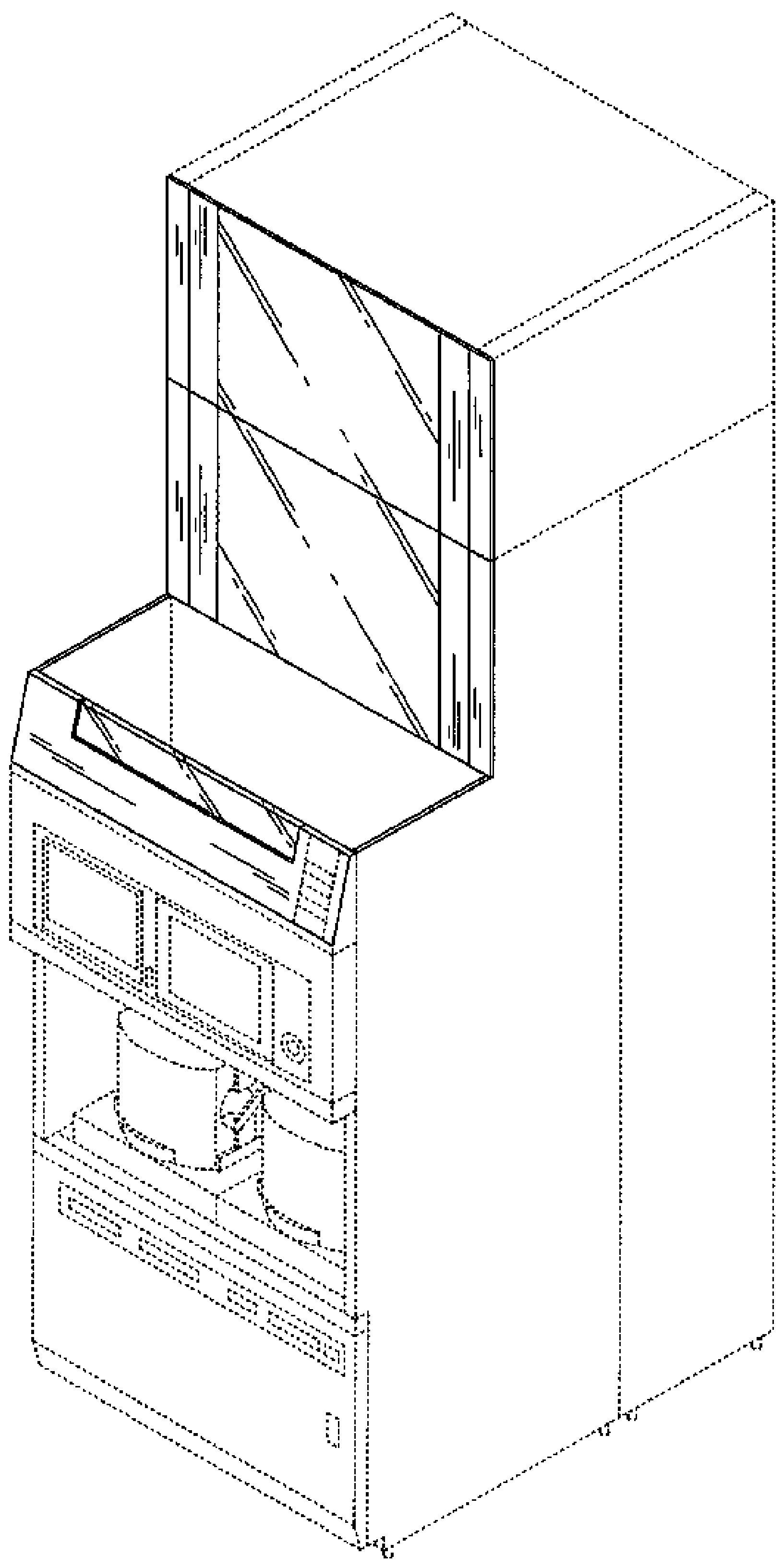
(57) **CLAIM**

We claim the ornamental design for a semiconductor manufacturing equipment, as shown and described.

DESCRIPTION

FIG. **1** is a front, top and right side perspective view of an semiconductor manufacturing equipment showing our new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a top plan view thereof;
FIG. **5** is a bottom plan view thereof;
FIG. **6** is a left side elevational view thereof; and,
FIG. **7** is a right side elevational view thereof.
The broken line showing of the "semiconductor manufacturing equipment" is for the purpose of illustrating environmental structure and forms no part of the claimed design.

1 Claim, 5 Drawing Sheets



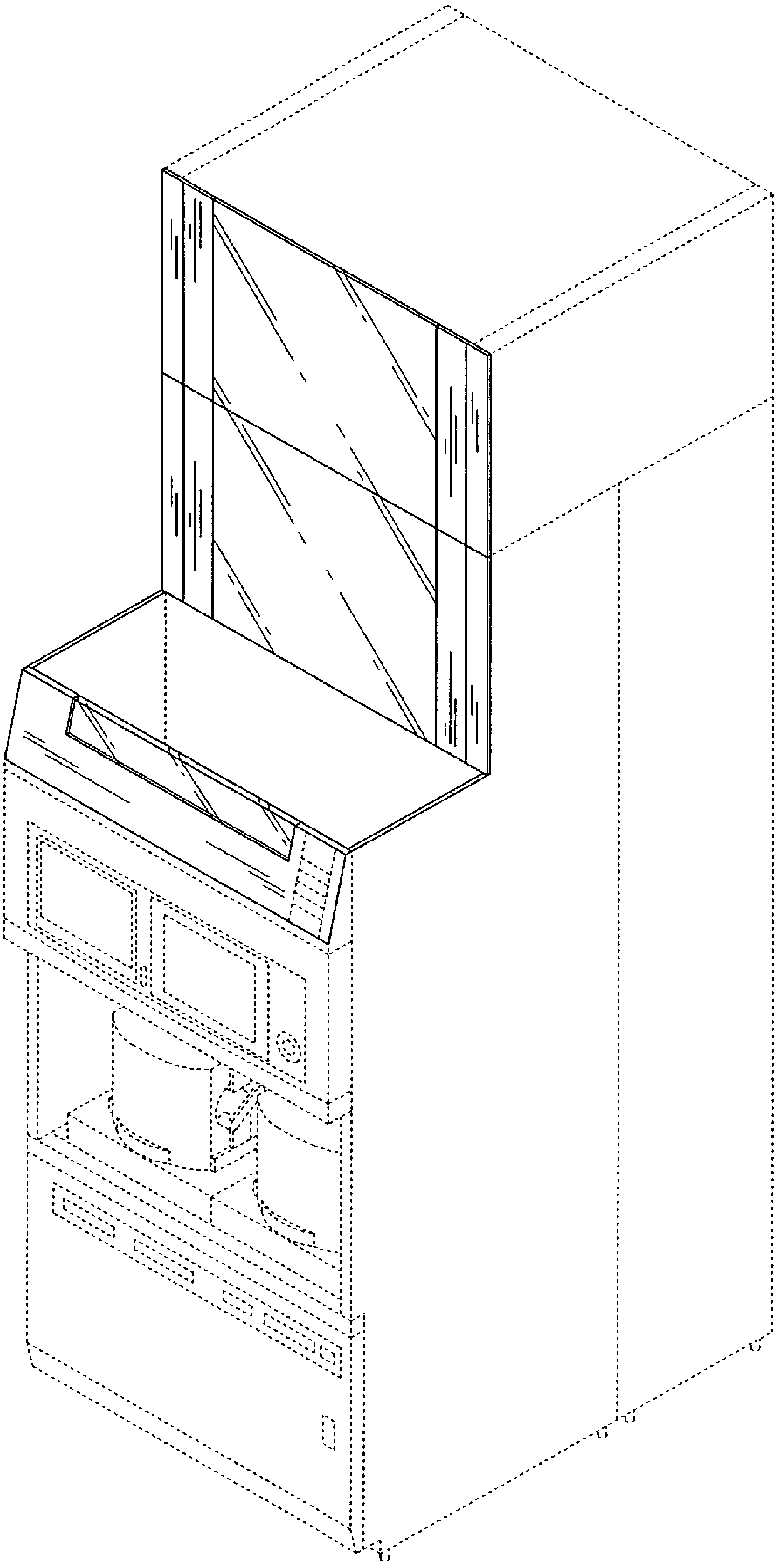


FIG. 1

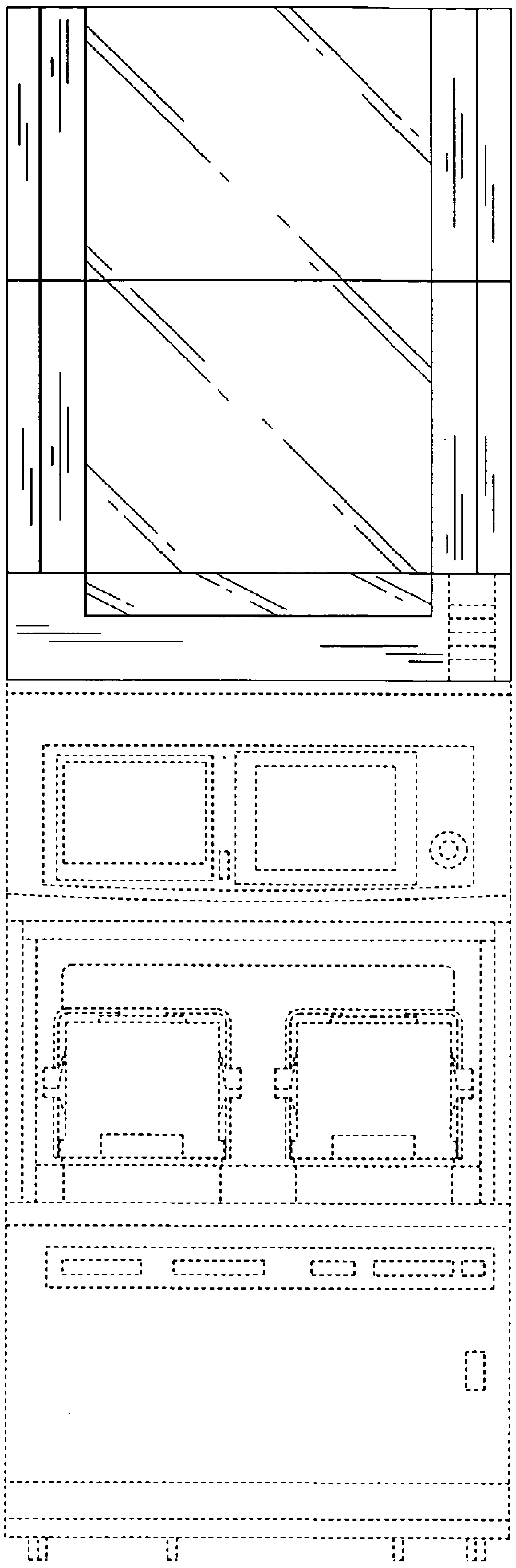


FIG. 2

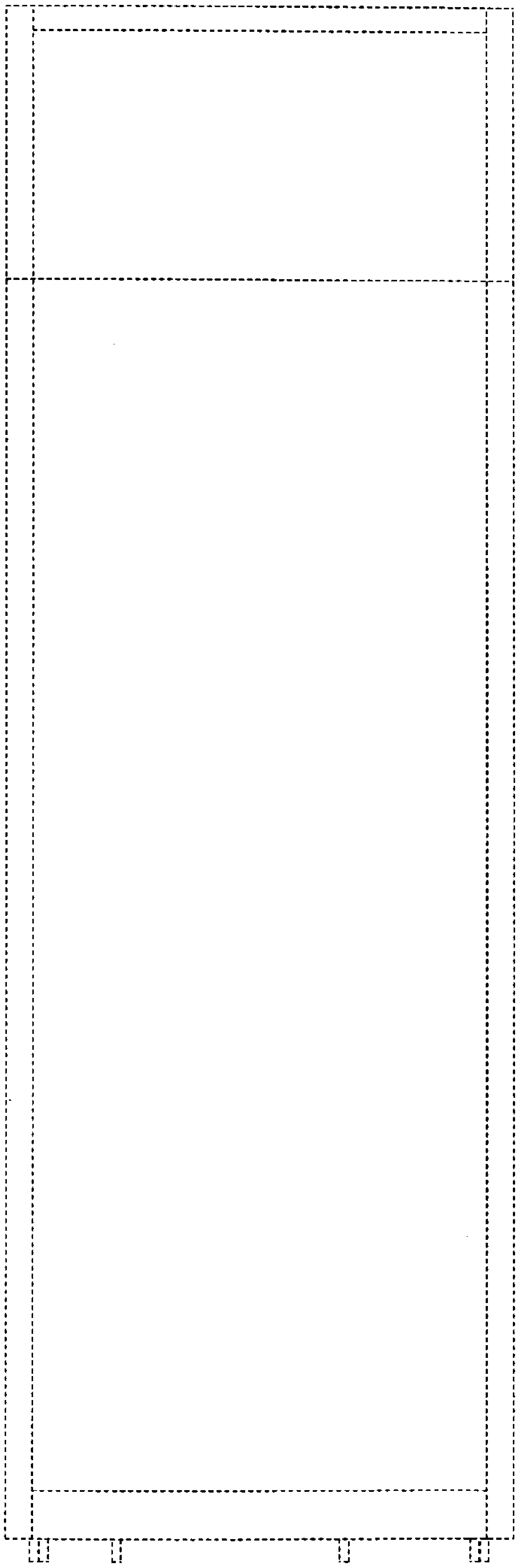


FIG. 3

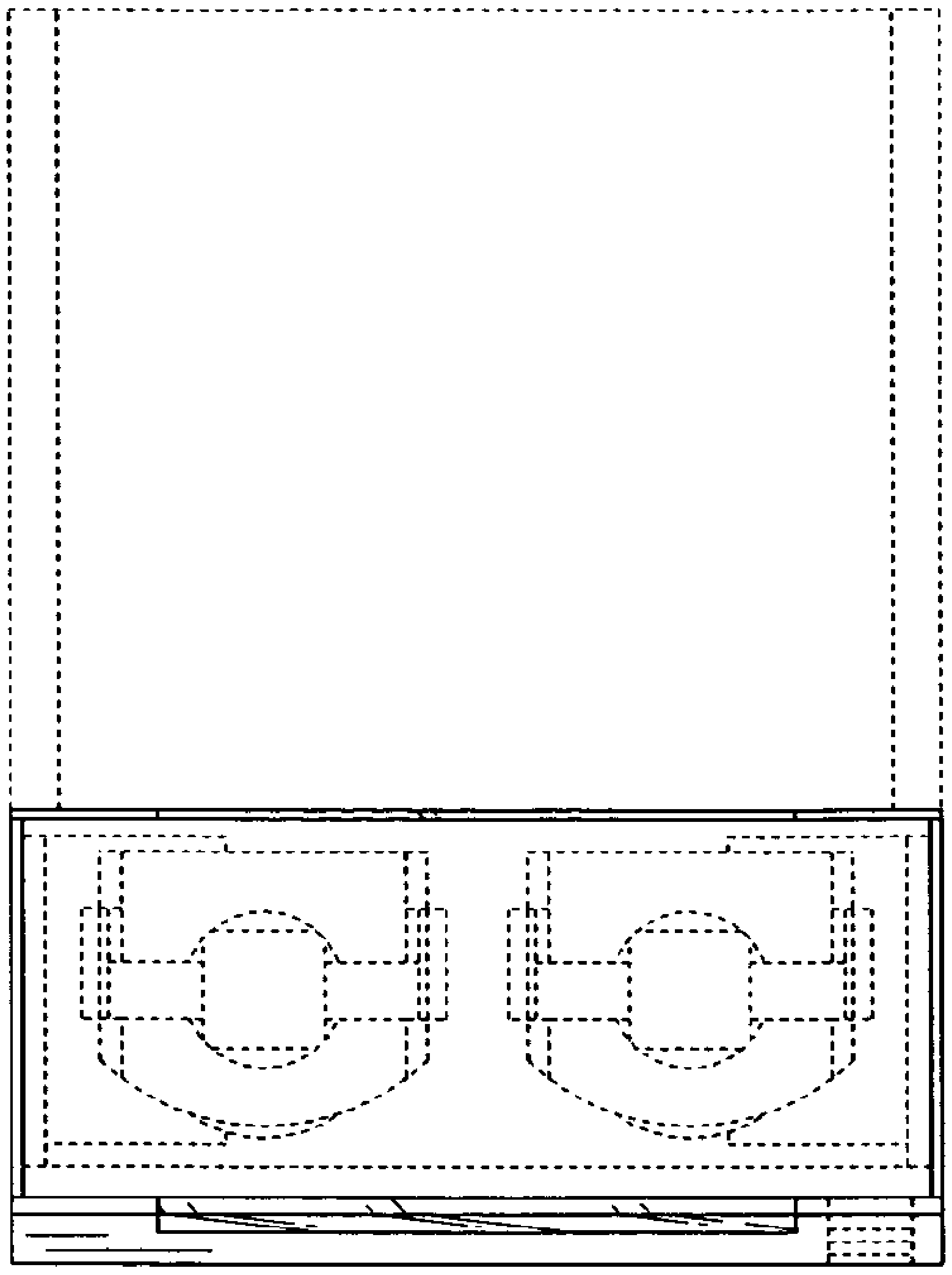


FIG. 4

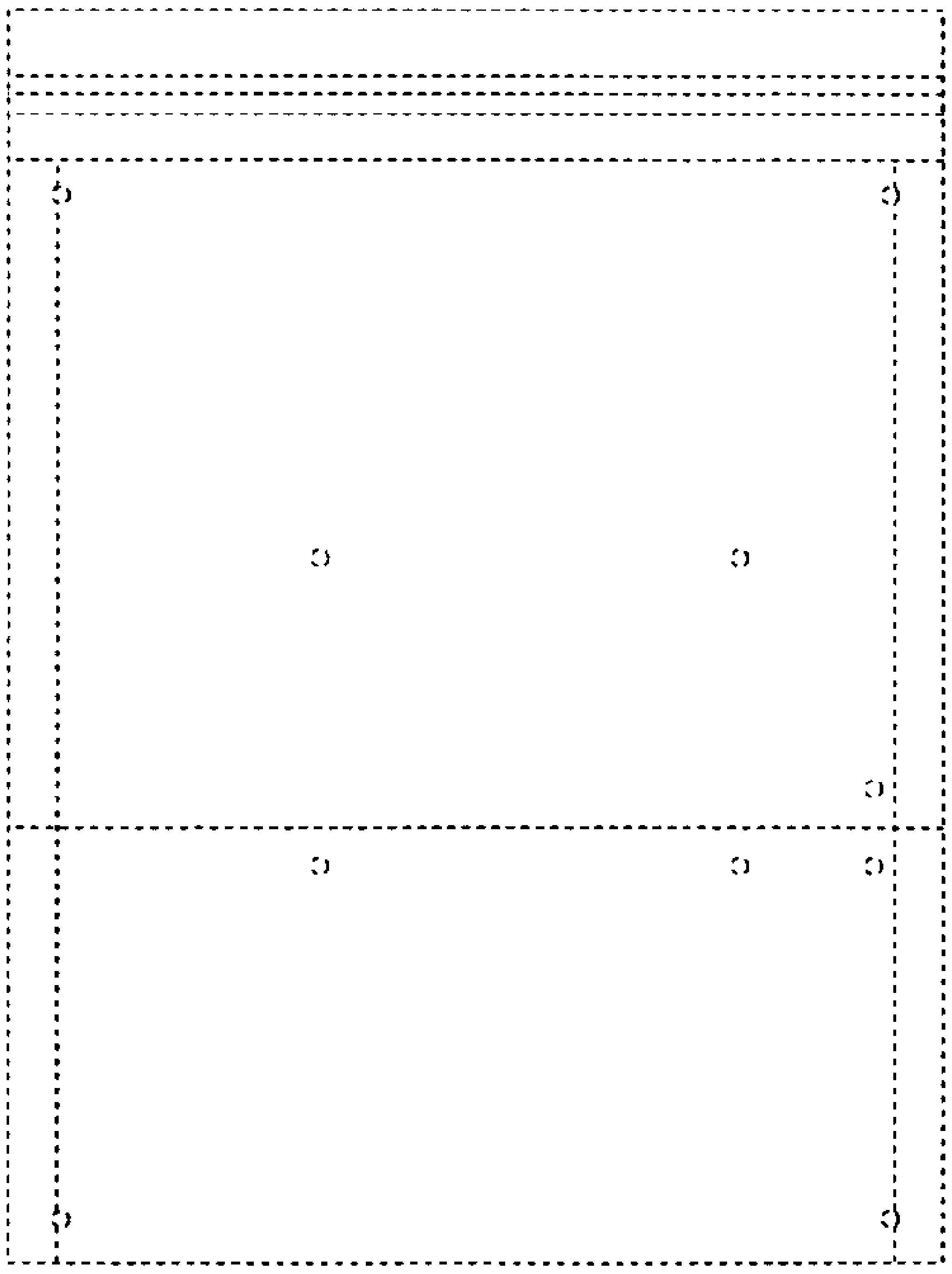


FIG. 5

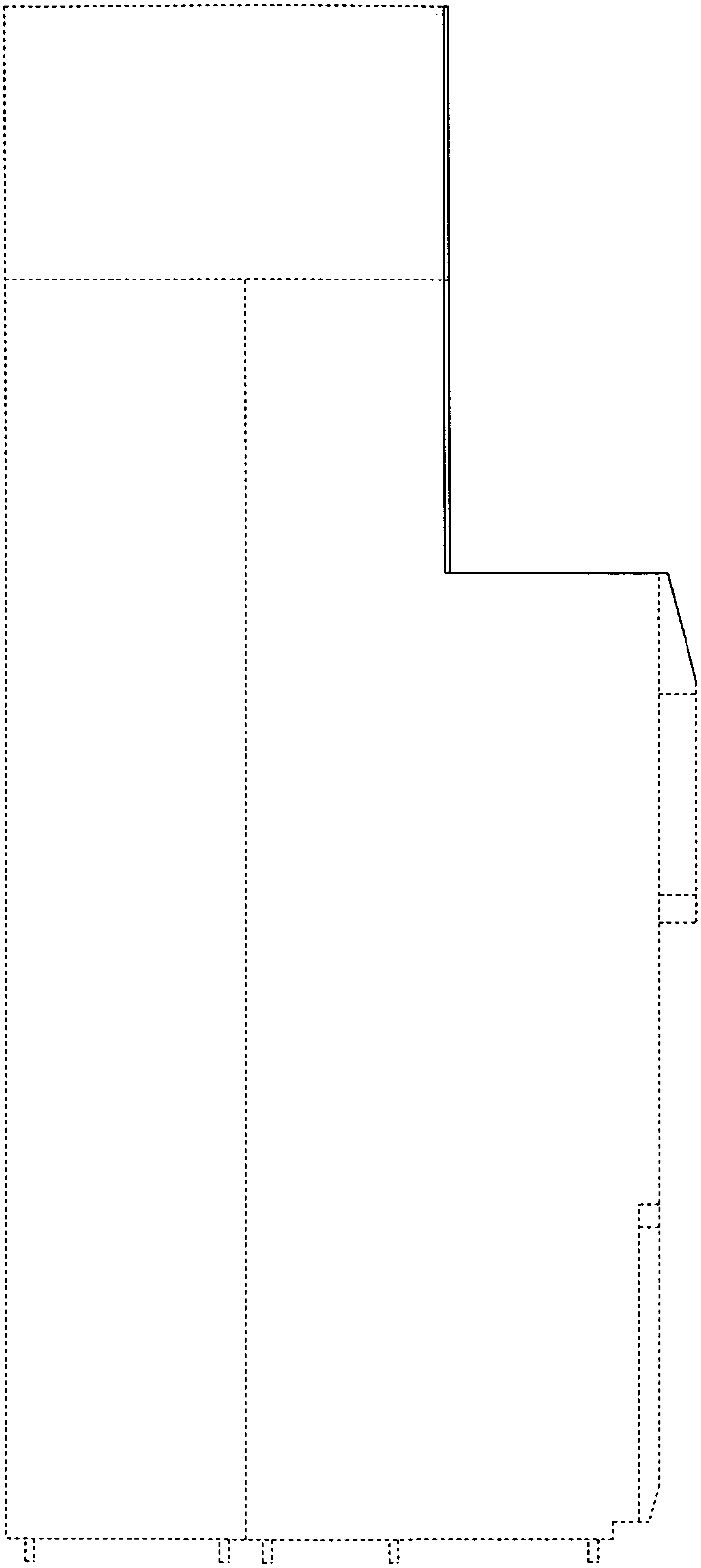


FIG. 6

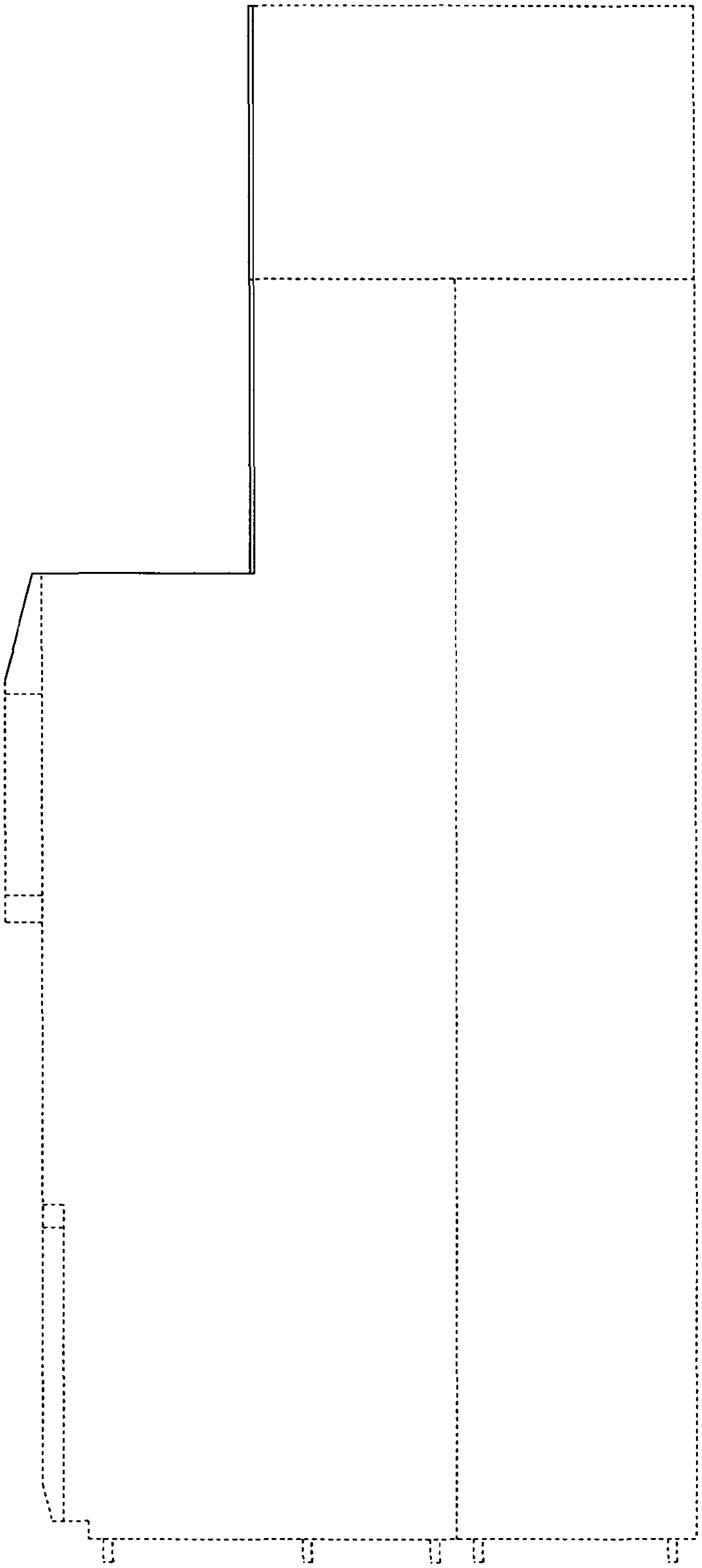


FIG. 7